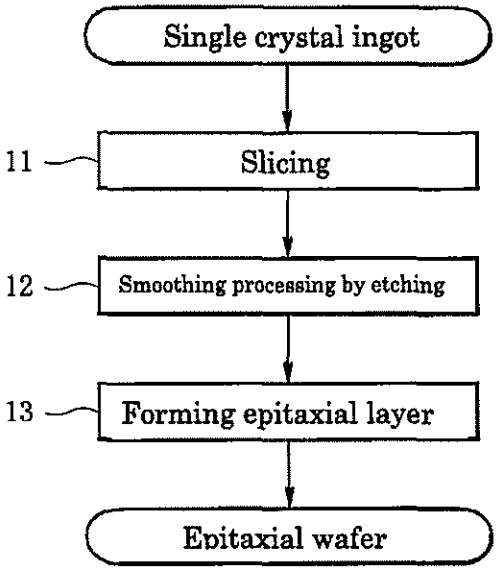
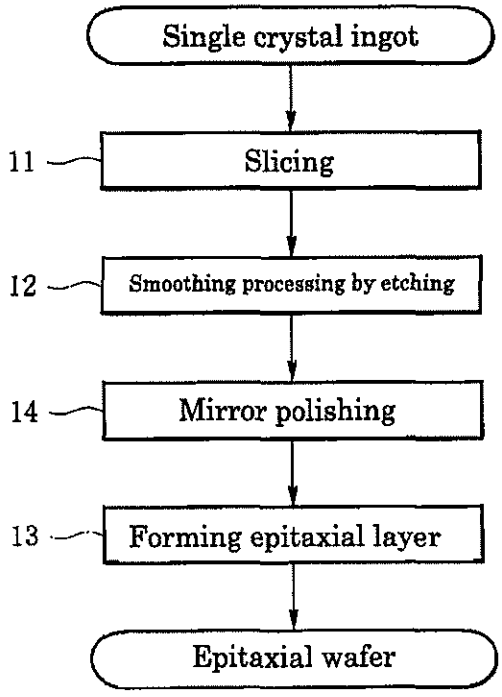
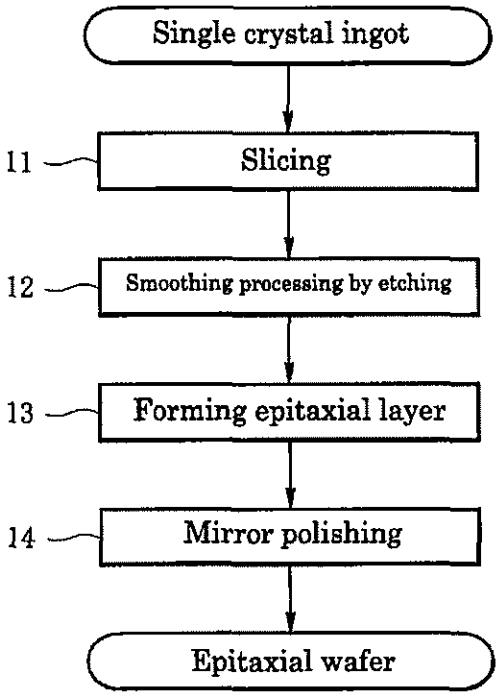
[Fig.1]


Single crystal ingot
11
Slicing
12
Smoothing processing by etching
13
Forming epitaxial layer
Epitaxial wafer

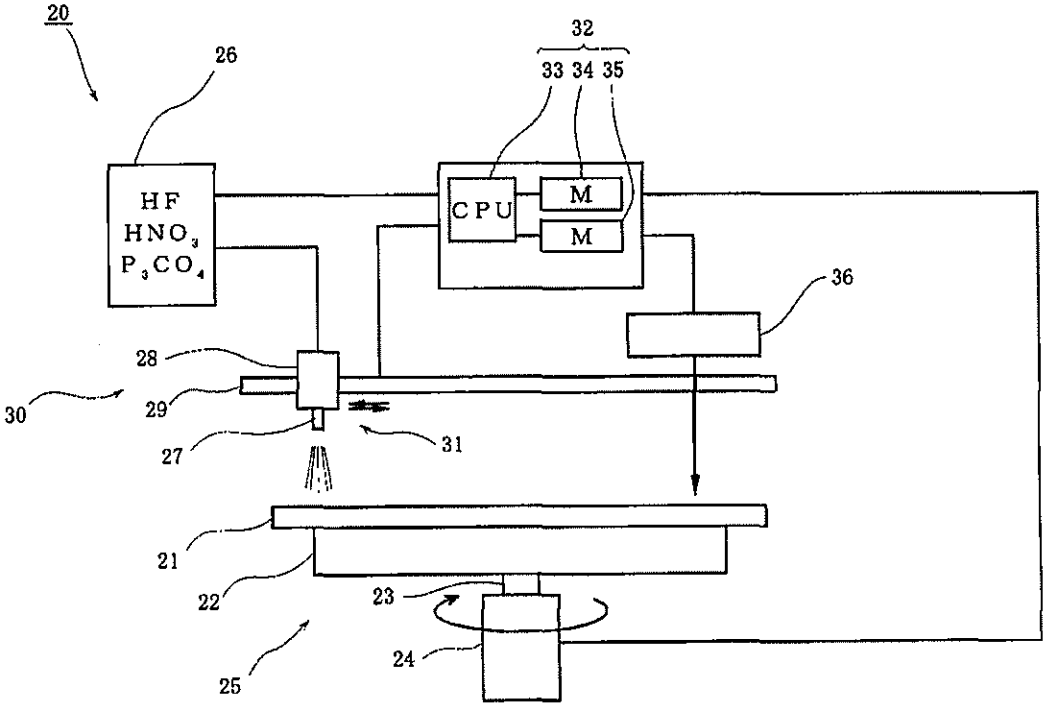
[Fig.2]


Single crystal ingot
11
Slicing
12
Smoothing processing by etching
14
Mirror polishing
13
Forming epitaxial layer
Epitaxial wafer

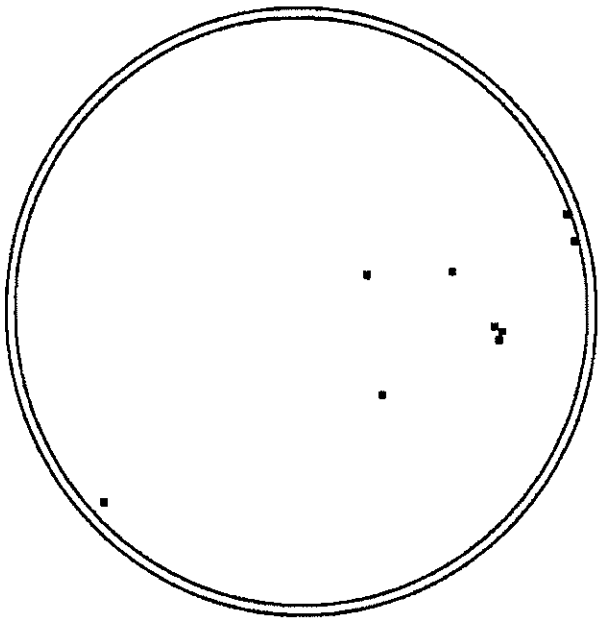
[Fig.3]


Single crystal ingot
11
Slicing
12
Smoothing processing by etching
13
Forming epitaxial layer
14
Mirror polishing
Epitaxial wafer

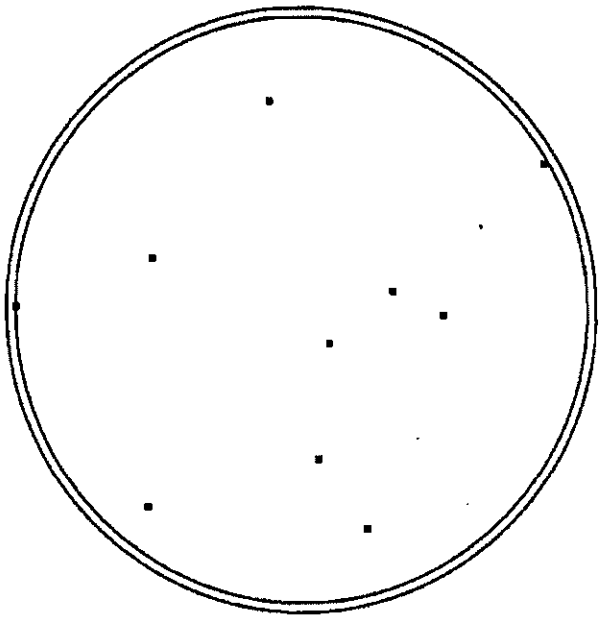
[Fig.4]


20
26
32
33 34 35
HF
HNO3
P3CO4
CPU
M
M
36
28
30
29
27
31
21
22
23
24
25

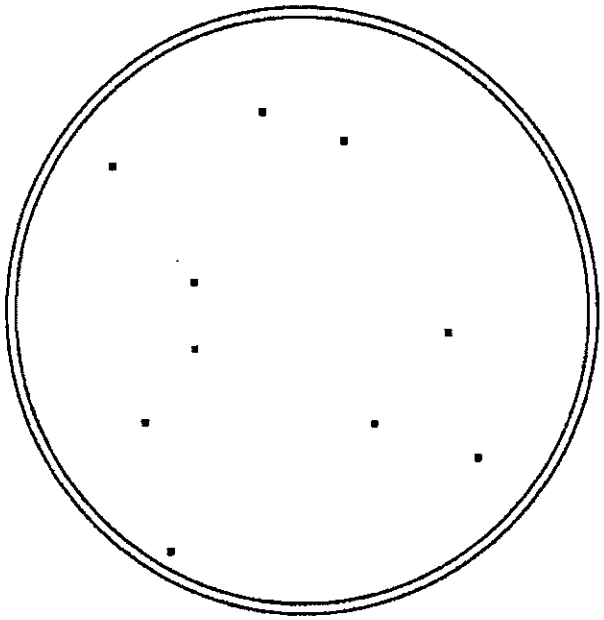
[Fig.5]



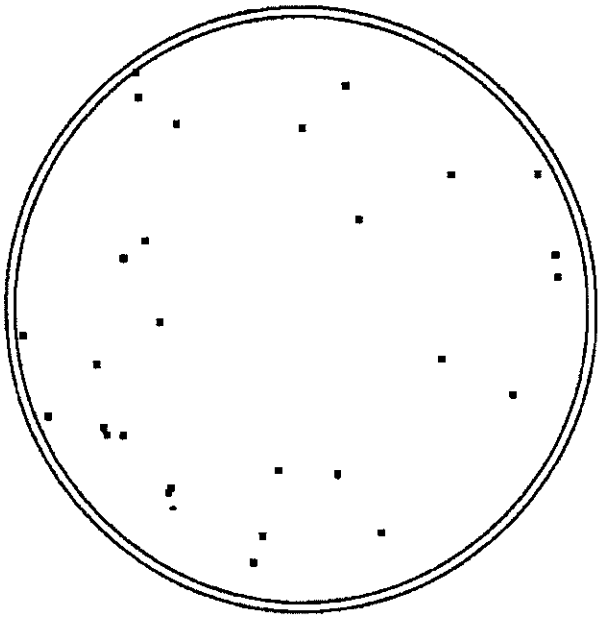
[Fig.6]



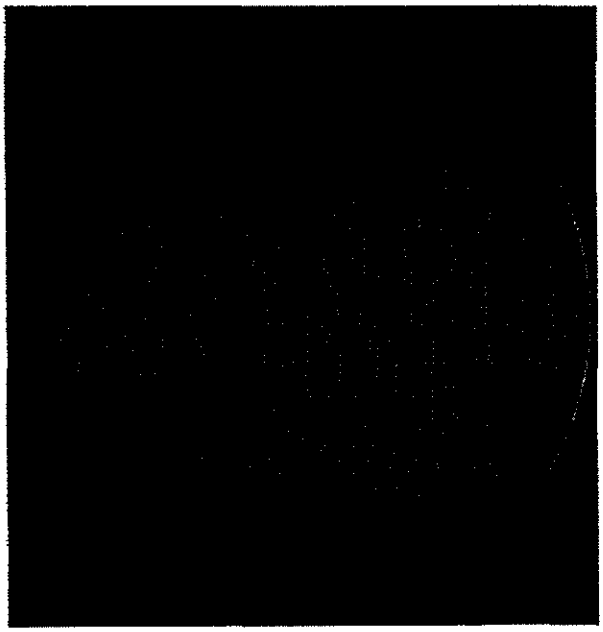
[Fig.7]



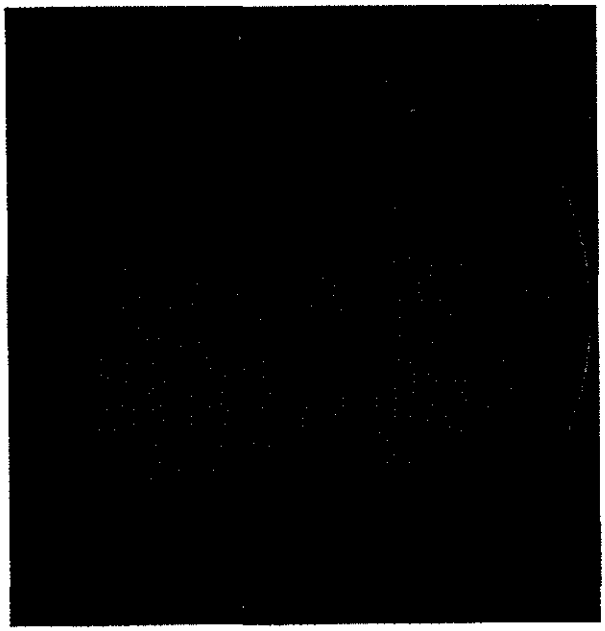
[Fig.8]



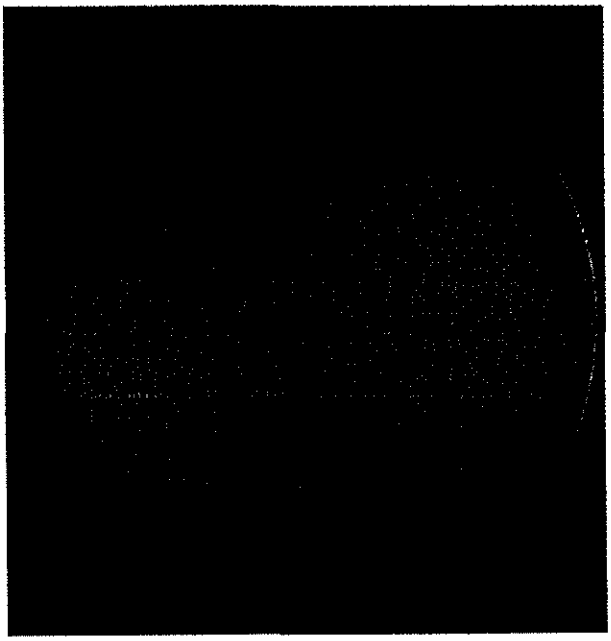
[Fig.9]



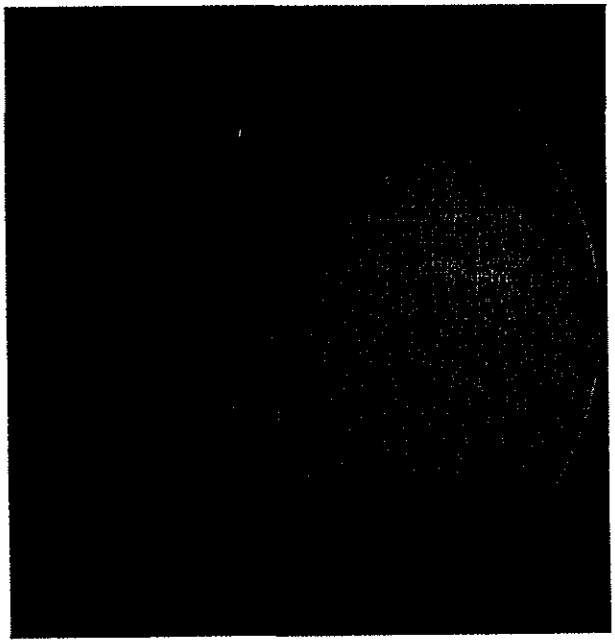
[Fig.10]



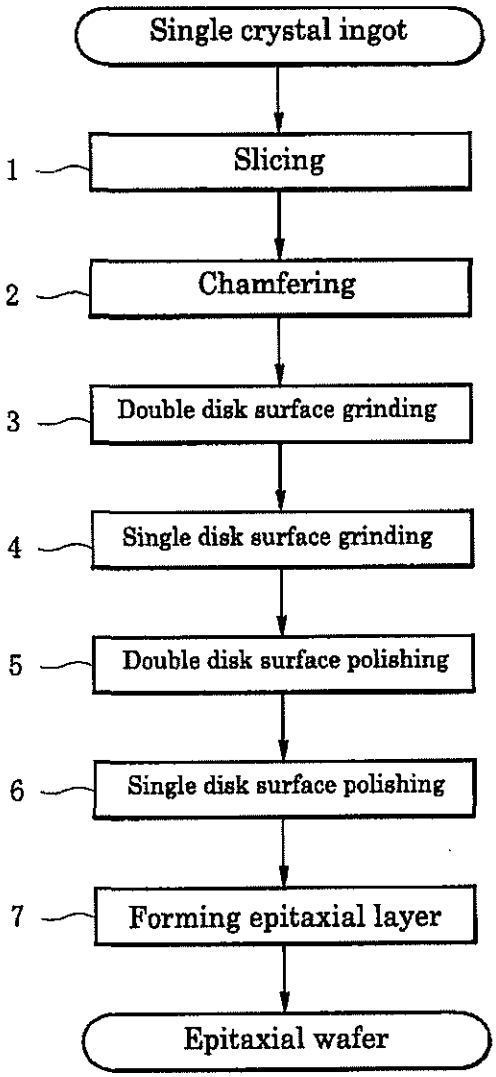
[Fig.11]



[Fig.12]



[Fig.13]


Single crystal ingot
1
Slicing
2
Chamfering
3
Double disk surface grinding
4
Single disk surface grinding
5
Double disk surface polishing
6
Single disk surface polishing
7
Forming epitaxial layer
Epitaxial wafer